

# INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

#### 03-Dec-2005

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #15130

TITLE: Initial notification of intent to dual source devices at ONCR and ONPY1 in Slovakia.

**EFFECTIVE DATE: 03-Apr-2006** 

AFFECTED CHANGE CATEGORY: ON Semiconductor Fab Site

**AFFECTED PRODUCT DIVISION:** Analog Power Management

## FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Alan Garlington rpr180@onsemi.com>

#### **NOTIFICATION TYPE:**

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

#### **DESCRIPTION AND PURPOSE:**

This is an Initial PCN to notify customers of the intent to qualify and dual source specific devices currently being processed at the ON Semiconductor M1 wafer fab in the Czech Republic (ONCR) to the existing ON Semiconductor wafer fab in Piestany, Slovakia (ONPY1). The ONPY1 fab will be used to provide additional capacity for these specified products. The existing design database currently in use at ONCR will be transferred to ONPY1 with no change to the functional circuit design. New mask sets will be generated which will incorporate required process control and alignment patterns. Full electrical characterization and bench analysis will be performed on all devices transferred to ensure no change to device functionality or data sheet electrical specifications.

As this is an initial PCN only, a final PCN will be issued at least 60 days prior to actual conversion. Final PCN's will be issued as the specific devices are prepared for release in the new wafer facility and will contain specific dates for each device. Samples will be available per the Final PCN schedule.

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#### **QUALIFICATION PLAN:**

MC1413, MC7805, MC7812 & MC33063 devices will be process qualified based on similarity to the LM224 & LM239 devices which run on the same processes and were qualified previously as shown below. Each device series will have temperature characterization, ESD (HBM, MM, CDM) and latch up evaluation performed on three assembly lots, as well as any necessary bench analysis. In addition, probe and final test yield analysis will be completed to ensure performance is well matched to the source fabrication facility.

Three assembly lots of LM224D and two assembly lots of LM239N, along with the associated control lots were built and qualified to plan below. No failures were observed on any of the lots using the qualification plan described below.

3x lots LM224D
Test Conditions EndPoint
Autoclave 121C,100%RH,15psig 96 hours
Temp Cycle 150C/-65C 500 cycles
HAST 130C,85%RH,18psig 96 hours
HTSL 175C 504 hours
HTOL Ta = 145C 504 hours
PC MSL1 260C Test 3x reflow

2x lots LM239N
Test Conditions EndPoint
Autoclave 121C,100%RH,15psig 96 hours
Temp Cycle 150/-65C 1000 cycles
HAST 130C,85%RH,18psig 96 hours
HTOL Ta = 125C 1008 hours

# AFFECTED DEVICE LIST:

#### Part

MC1413BD

MC1413BDG

MC1413BDR2

MC1413BDR2G

MC1413BP

MC1413BPG

MC1413D

MC1413DG

MC1413DR2

MC1413DR2G

MC1413P

MC1413PG

MC33063AD

MC33063ADG

MC33063ADR2

MC33063ADR2G

MC33063AP1

MC33063AP1G

MC33063AVD

MC33063AVDG

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#### AFFECTED DEVICE LIST:

#### Part

MC33063AVDR2

MC33063AVDR2G

MC33063AVP

MC33063AVPG

MC34063AD

MC34063ADG

MC34063ADR2

MC34063ADR2G

MC34063AM

MC34063AMEL

MC34063AMELG

MC34063AP1

MC34063AP1G

MC34063BD

MC34063BDG

MC34063BDR2

MC34063BDR2G

MC7805BD2T

MC7805BD2TG

MC7805BD2TR4

MC7805BD2TR4G

MC7805BDT

MC7805BDTG

MC7805BDTRK

MC7805BDTRKG

MC7805BT

MC7805BTG

MC7805CD2T

MC7805CD2TG

MC7805CD2TR4

MC7805CD2TR4G

MC7805CDT

MC7805CDTG

MC7805CDTRK

MC7805CDTRKG

MC7805CT

MC7805CTG

MC7812BD2T

MC7812BD2TG MC7812BD2TR4

MC7812BD2TR4G

MC7812BDT

MC7812BDTG

MC7812BDTRK

MC7812BDTRKG

MC7812BT

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# **Initial Product/Process Change Notification #15130**

#### AFFECTED DEVICE LIST:

#### Part

MC7812BTG

MC7812CD2T

MC7812CD2TG

MC7812CD2TR4

MC7812CD2TR4G

MC7812CDT

MC7812CDTG

MC7812CDTRK

MC7812CDTRKG

MC7812CT

MC7812CTG

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